



Material Content Data Sheet



Sales Product Name		BTN8982TA		Issued		1. August 2018		
MA#		MA001936852						
Package		PG-TO263-7-1		Weight*		1532.41 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.214	0.47	0.47	4708	4708
leadframe	inorganic material	phosphorus	7723-14-0	0.243	0.02		159	
	non noble metal	iron	7439-89-6	0.810	0.05		528	
wire	non noble metal	copper	7440-50-8	808.613	52.78	52.85	527673	528360
	non noble metal	aluminium	7429-90-5	6.176	0.40	0.40	4030	4030
encapsulation	organic material	carbon black	1333-86-4	8.791	0.57		5737	
	plastics	epoxy resin	-	96.702	6.31		63104	
	inorganic material	silicondioxide	60676-86-0	480.578	31.36	38.24	313609	382450
leadfinish	non noble metal	tin	7440-31-5	13.037	0.85	0.85	8507	8507
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.212	0.01	0.01	139	140
glue	plastics	Polyimide	26023-21-2	0.396	0.03	0.03	259	259
solder	non noble metal	tin	7440-31-5	0.066	0.00		43	
	noble metal	silver	7440-22-4	0.082	0.01		54	
	non noble metal	lead	7439-92-1	3.141	0.20	0.21	2050	2147
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	iron	7439-89-6	0.106	0.01		69	
	non noble metal	copper	7440-50-8	106.210	6.93	6.94	69309	69399
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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